

### SMD ▪ Low Power LED 67-21/LK2C-S5757B4B7B2/2T



#### Features

- PLCC-2 package
- Top view white LED
- High luminous intensity output
- Wide viewing angle
- Pb-free
- RoHS compliant

#### Description

The Everlight 67-21 package has high efficacy, high CRI, low power consumption, wide viewing angle and a compact form factor. These features make this package an ideal LED for all lighting applications.

#### Applications

- General lighting
- Decorative and Entertainment Lighting
- Indicators
- Illumination
- Switch lights

## Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	Cool White	Water Clear

## Absolute Maximum Ratings (T<sub>Soldering</sub>=25 )

Parameter	Symbol	Rating	Unit
Forward Current	I <sub>F</sub>	30	mA
Peak Forward Current (Duty 1/10 @10ms)	I <sub>FP</sub>	100	mA
Power Dissipation	P <sub>d</sub>	110	mW
Operating Temperature	T <sub>opr</sub>	-40 ~ +85	
Storage Temperature	T <sub>stg</sub>	-40 ~ +100	
Thermal Resistance (Junction / Soldering point)	R <sub>th J-S</sub>	65	/W
Junction Temperature	T <sub>j</sub>	125	
Soldering Temperature	T <sub>sol</sub>	Reflow Soldering : 260 Hand Soldering : 350	for 10 sec. for 3 sec.

**Note:**

The products are sensitive to static electricity and must be carefully taken when handling products

## Electro-Optical Characteristics (T<sub>Soldering</sub>=25 )

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Flux	Φ	7.0	-----	9.0	lm	I <sub>F</sub> =20mA
Forward Voltage	V <sub>F</sub>	2.9	-----	3.6	V	I <sub>F</sub> =20mA
Viewing Angle	2θ <sub>1/2</sub>	-----	120	-----	deg	I <sub>F</sub> =20mA
Color Rendering Inde.	Ra	70	-----	-----		I <sub>F</sub> =20mA
Reverse Current	I <sub>R</sub>	-----	-----	50	μA	V <sub>R</sub> =5V

**Notes:**

1. Tolerance of Luminous Flux: ±11%.
2. Tolerance of Forward Voltage : ±0.1V.
3. Tolerance of Color Rendering Index: ±2

**Bin Range of Luminous Flux**

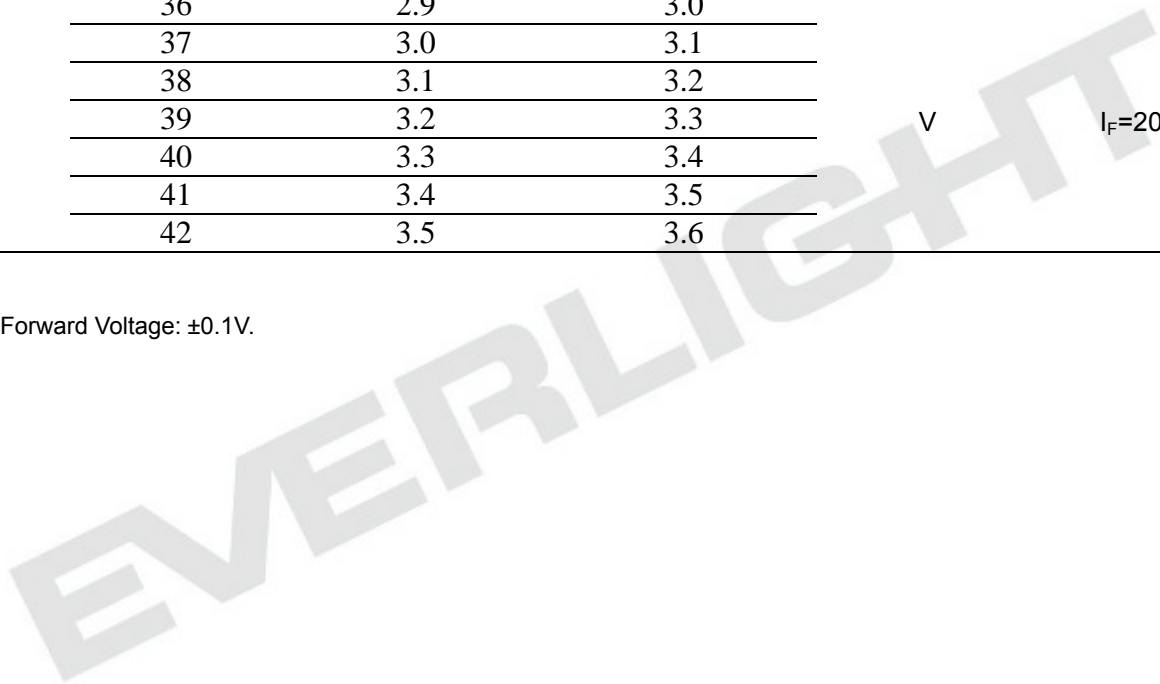
Bin Code	Min.	Max.	Unit	Condition
B4	7.0	7.5	lm	I <sub>F</sub> =20mA
B5	7.5	8.0		
B6	8.0	8.5		
B7	8.5	9.0		

Note:  
 Tolerance of Luminous Flux: ±11%

**Bin Range of Forward Voltage**

Group	Bin Code	Min.	Max.	Unit	Condition
B2	36	2.9	3.0	V	I <sub>F</sub> =20mA
	37	3.0	3.1		
	38	3.1	3.2		
	39	3.2	3.3		
	40	3.3	3.4		
	41	3.4	3.5		
	42	3.5	3.6		

Note:  
 Tolerance of Forward Voltage: ±0.1V.

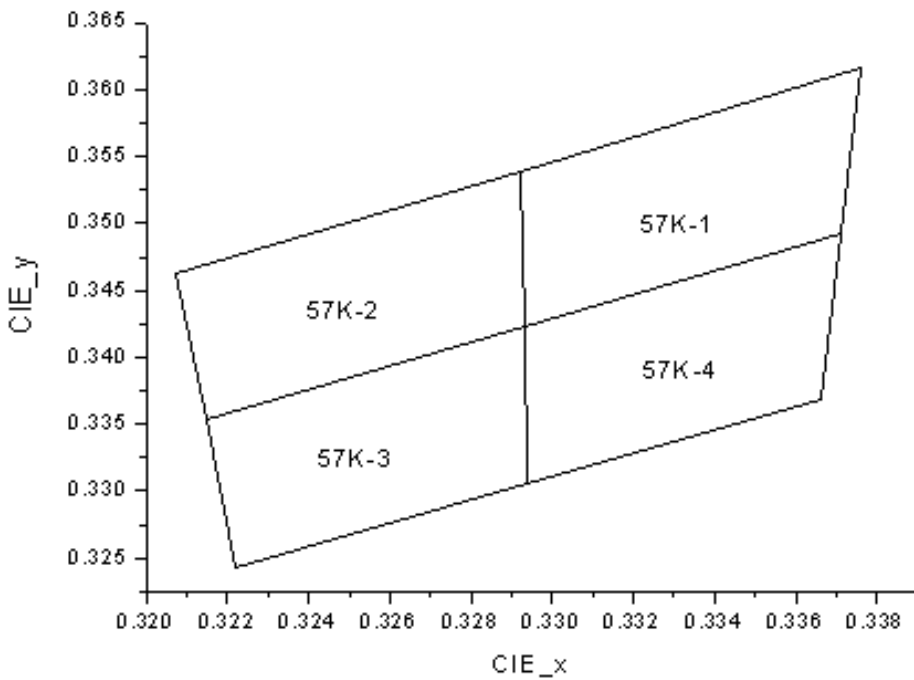


**Bin Range of Chromaticity Coordinates**

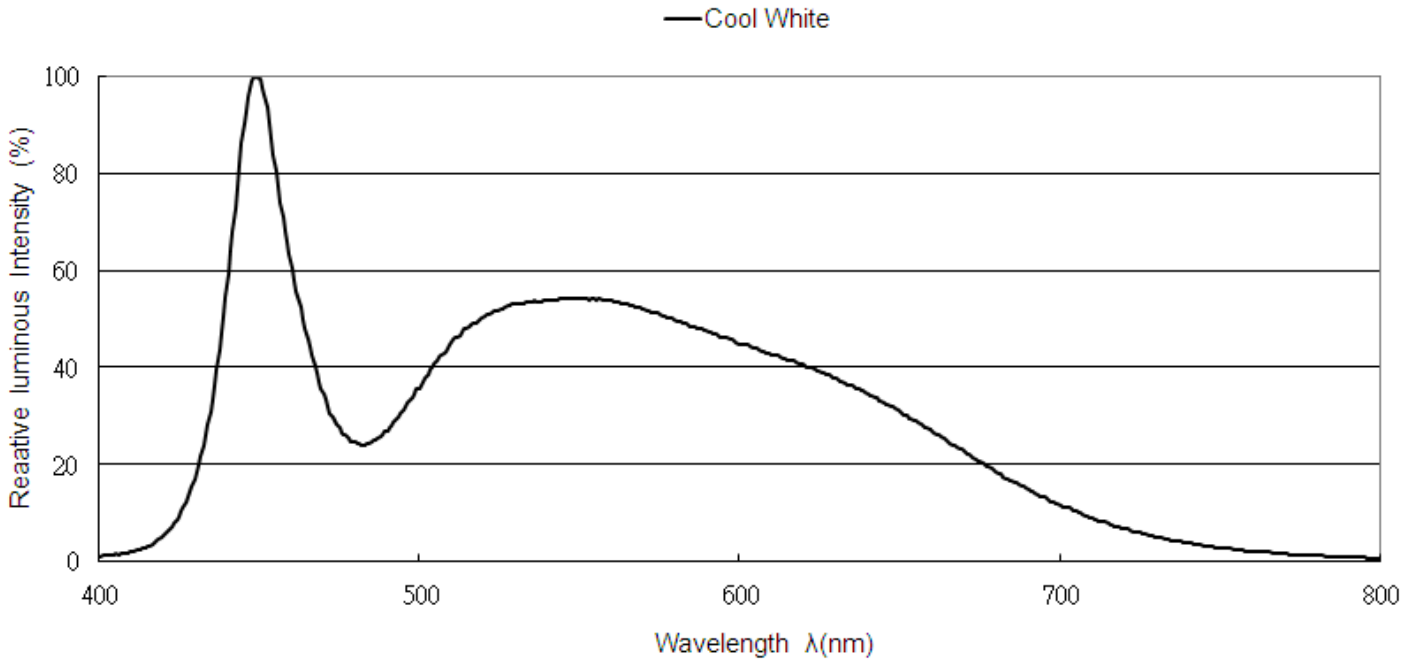
CCT	Bin Code	CIE_x	CIE_y	Bin Code	CIE_x	CIE_y
5700K	57K-1	0.3376	0.3616	57K-3	0.3293	0.3423
		0.3292	0.3539		0.3215	0.3353
		0.3293	0.3423		0.3222	0.3243
		0.3371	0.3493		0.3294	0.3306
	57K-2	0.3292	0.3539	57K-4	0.3371	0.3493
		0.3207	0.3462		0.3293	0.3423
		0.3215	0.3353		0.3294	0.3306
		0.3293	0.3423		0.3366	0.3369

- Note:
1. The value is based on driving current by 20mA.
  2. Tolerance of Chromaticity Coordinates: ±0.01

**The C.I.E. 1931 Chromaticity Diagram**



**Spectrum Distribution**



**Typical Electro-Optical Characteristics Curves**

Fig.1 - Forward Voltage Shift vs. Junction Temperature

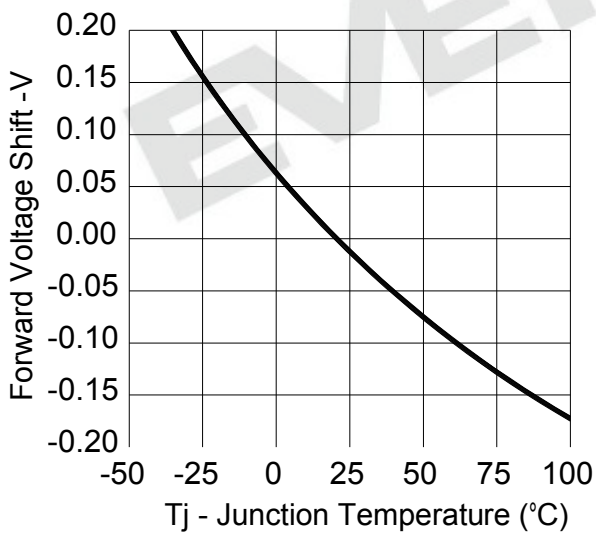
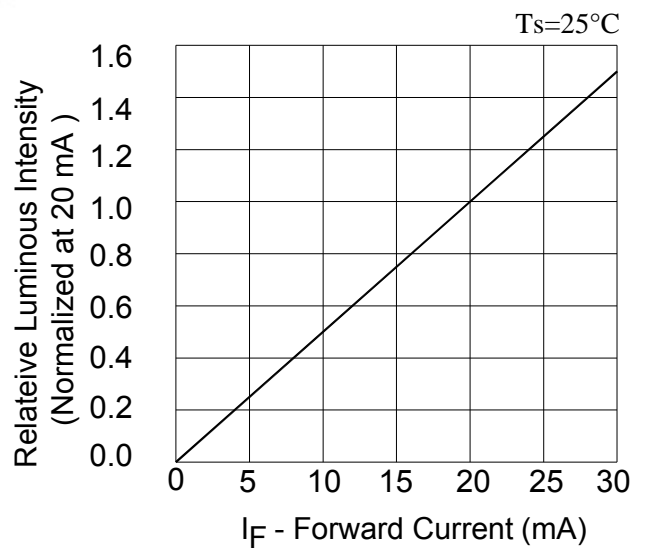


Fig.2 - Relative Luminous Intensity vs. Forward Current



Typical Electro-Optical Characteristics Curves

Fig.3 - Relative Luminous Intensity vs. Junction Temperature

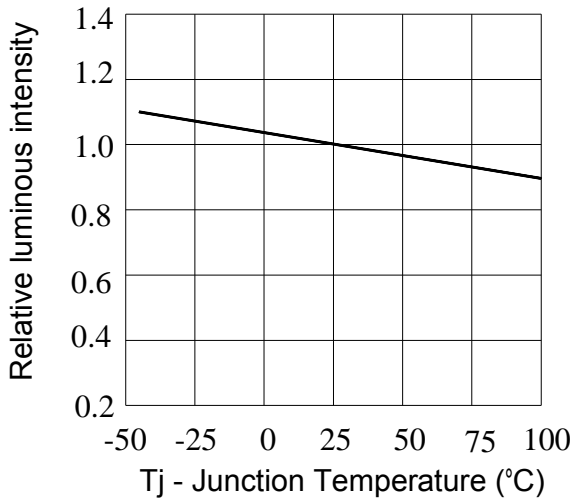


Fig.4 - Forward Current vs. Forward Voltage

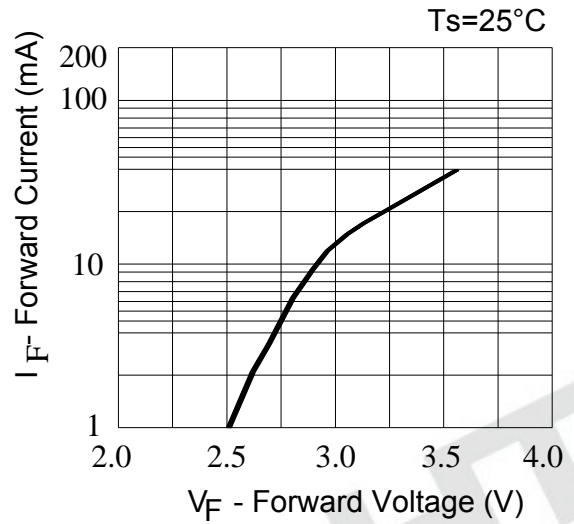


Fig.5 - Max. Driving Forward Current vs. Soldering Temperature

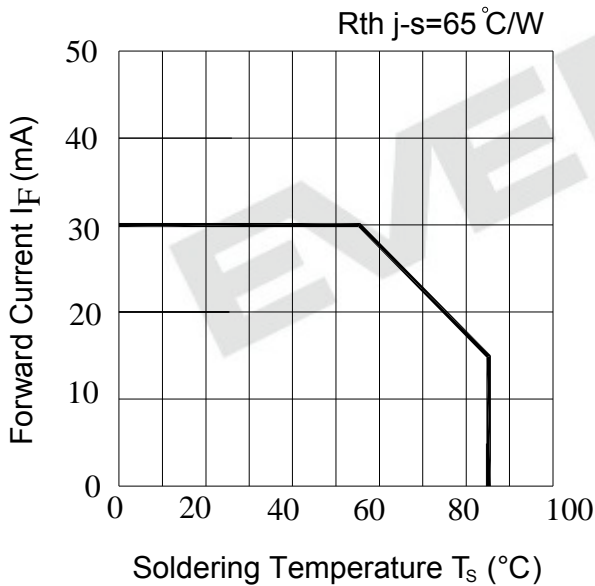
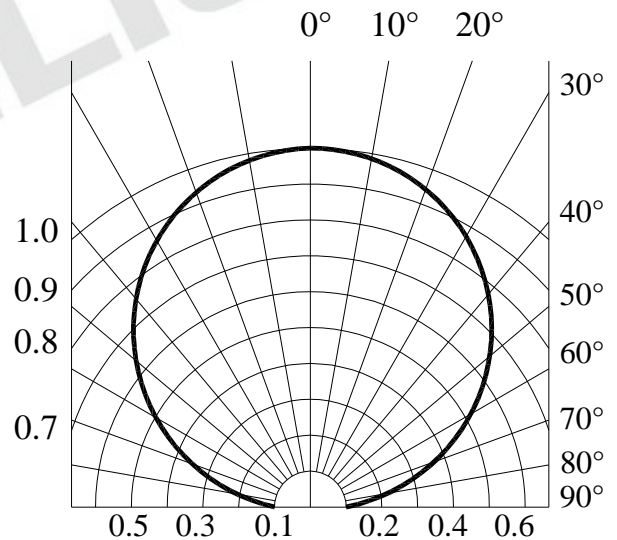
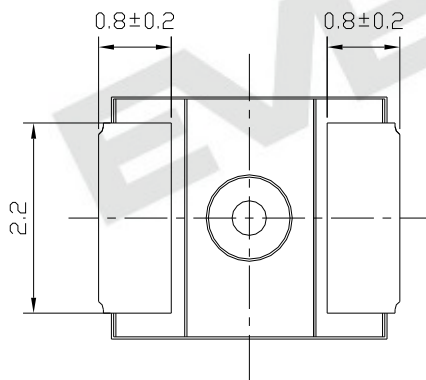
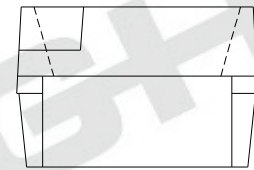
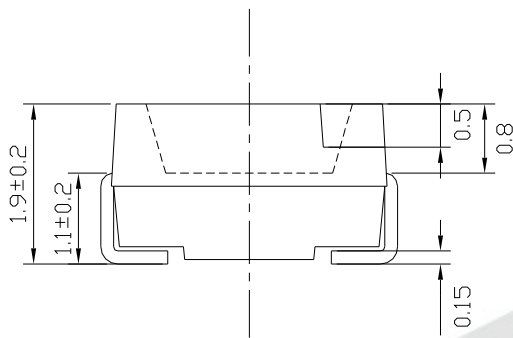
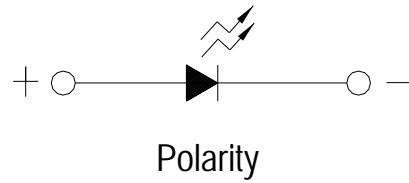
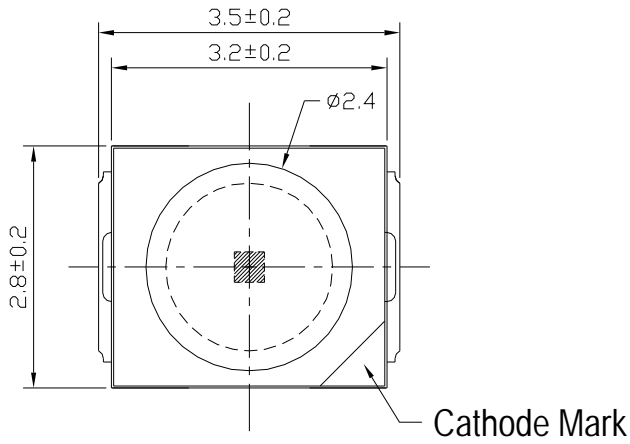


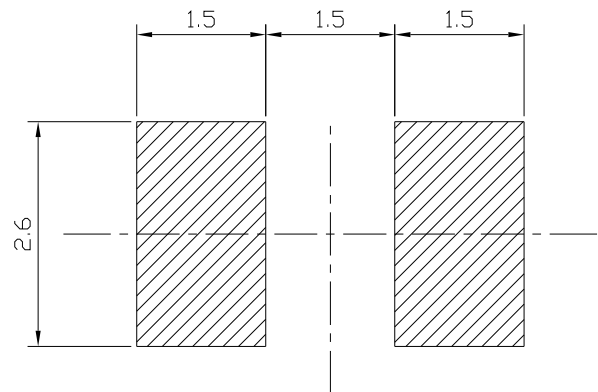
Fig.6 - Radiation Diagram



### Package Dimension



### Recommended Solder Pad



Note:  
Tolerance unless mentioned is  $\pm 0.2$ mm; Unit = mm

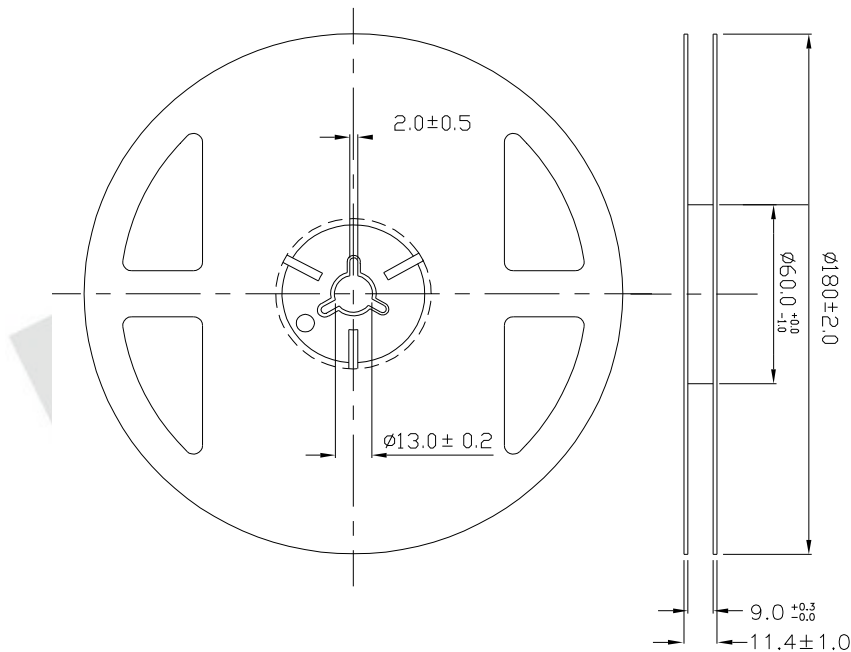
**Moisture Resistant Packing Materials**

**Label Explanation**



- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

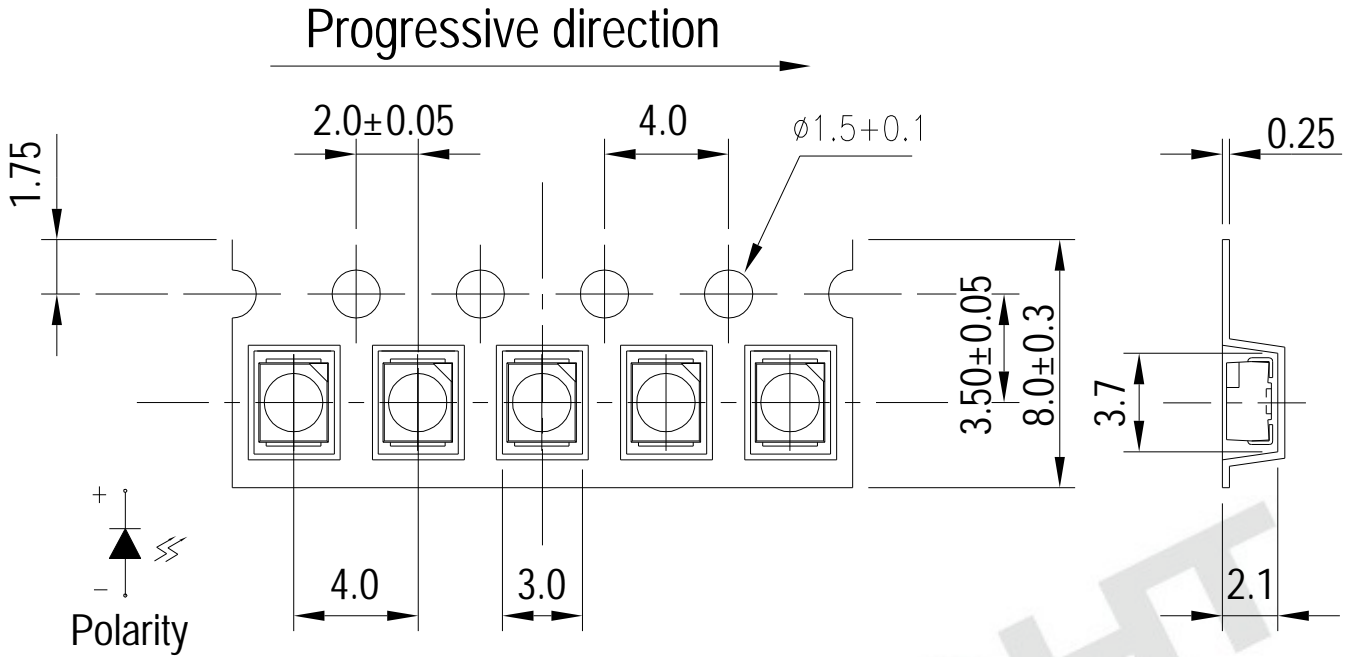
**Reel Dimensions**



Note:  
 Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm



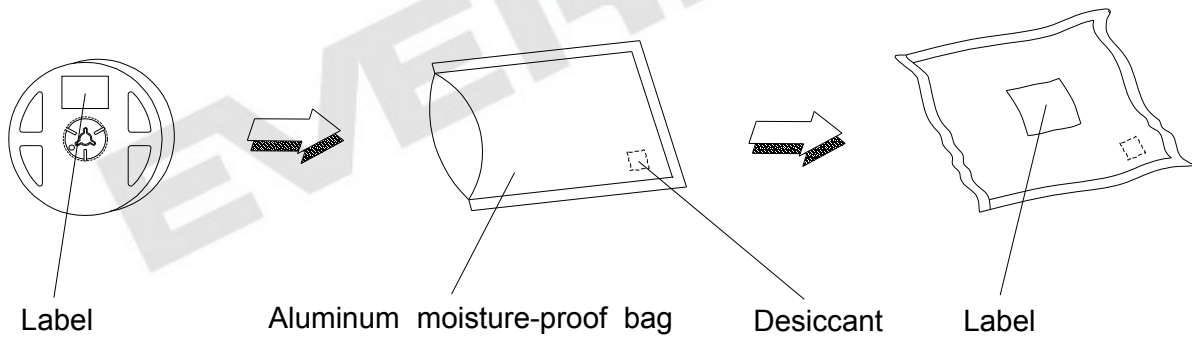
Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Note:

1. Tolerance unless mentioned is  $\pm 0.1$ mm; Unit = mm
2. Minimum packing amount is 250/500/1000/2000 pcs per reel

Moisture Resistant Packing Process



## Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

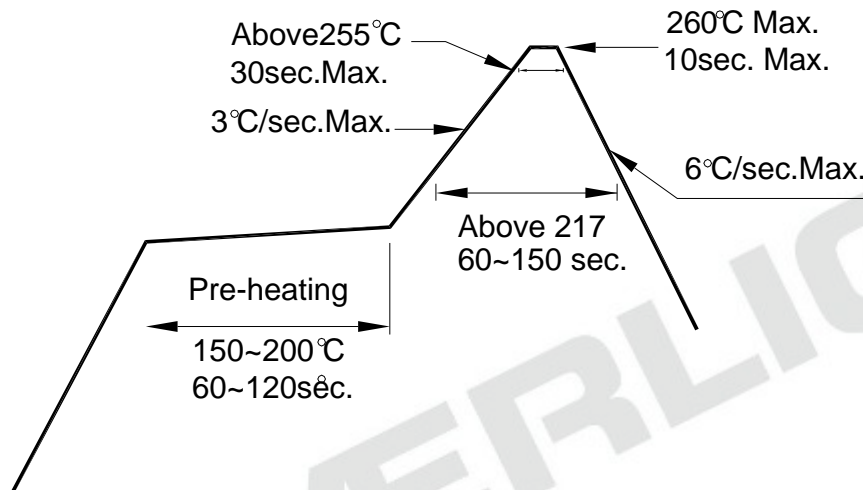
Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260 /10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H : +100 5min 10 sec L : -10 5min	200 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100 15min 5 min L : -40 15min	200 Cycles	22 PCS.	0/1
4	High Temperature/Humidity Reverse Bias	Ta=85 ,85%RH	1000 Hrs.	22 PCS.	0/1
5	High Temperature/Humidity Operation	Ta=85 ,85%RH, I <sub>F</sub> = 20 mA	1000 Hrs.	22 PCS.	0/1
6	Low Temperature Storage	Ta=-40	1000 Hrs.	22 PCS.	0/1
7	High Temperature Storage	Ta=85	1000 Hrs.	22 PCS.	0/1
8	Low Temperature Operation Life	Ta=-40 , I <sub>F</sub> = 30 mA	1000 Hrs.	22 PCS.	0/1
9	High Temperature Operation/ Life#1	Ta=25 , I <sub>F</sub> = 30 mA	1000 Hrs.	22 PCS.	0/1
10	High Temperature Operation/ Life#2	Ta=55 , I <sub>F</sub> =30 mA	1000 Hrs.	22 PCS.	0/1
11	High Temperature Operation/ Life#3	Ta=85 , I <sub>F</sub> = 20 mA	1000 Hrs.	22 PCS.	0/1

## Precautions for Use

1. Over-current-proof  
Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).
2. Storage
  - 2.1 Do not open moisture proof bag before the products are ready to use.
  - 2.2 Before opening the package: The LEDs should be kept at 30 °C or less and 90%RH or less.
  - 2.3 After opening the package: The LED's floor life is 168 Hrs under 30 °C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
  - 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.  
Baking treatment: 60±5 °C for 24 hours.
3. Soldering Condition
  - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

#### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350 for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### 5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

